

Final Product Change Notification

202406011F01: LQFP144 20*20 Products Assembly Site Expansion to TFME-T

Note: This notice is NXP Company

Proprietary.

Issue Date: Jul 03, 2024 Effective Date: Oct 01, 2024

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Change Category

[]Wafer []Assembly []Test [X]Product Marking Fab []Design Process **Process Process** []Wafer []Assembly []Test []Mechanical Specification []Errata Fab Materials Equipment Materials []Wafer []Electrical [X]Assembly []Packing/Shipping/Labeling []Test Fab spec./Test Location Location Location coverage

[]Firmware[]Other

Notification Overview Description

NXP Semiconductors is announcing the assembly site expansion for the LQFP144 20*20 packages from current TongFu Microeletronics Co.,Ltd, Nantong. China (TFME) to Tongfu Tongke (Nantong) Microelectronics Co.,LTD (TFME-T). Assembly site expansion was successfully qualified adhering to NXP specifications. Please see the attached file(s) for additional details and contact your NXP sales or marketing representative for additional information.

Reason

Qualification of the TFME-T assembly Facility is to ensure manufacturing flexibility and customer supply assurance.

Identification of Affected Products

Top Side Marking

The first one/two characters of the third line will indicate assembly site:

XN=TFME VX=TFME-T

Product Availability

Sample Information

Samples are available from Jun 24, 2024

Sample Part Number: PK60FN1M0VLQ15 PIMXRT1024CAG4B Original Part Number: MK60FN1M0VLQ15 MIMXRT1024CAG4B

For other samples, NXP will provide upon customer's request, or customer contact Sales/Marketer.

Production

Planned first shipment Sep 30, 2024

Anticipated Impact on Form, Fit, Function, Reliability or Quality

No Impact on form, fit, function, reliability or quality

Disposition of Old Products

Site Expansion, no inventory depletion is needed.

Additional information

Self qualification: view online
Additional documents: view online
Timing and Logistics

In compliance with JEDEC J-STD-046, your acknowledgement of this change is expected by Aug 02, 2024.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Product Engineer

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At NXP Semiconductors we are constantly striving to improve our product and processes to ensure they reach the highest possible Quality Standards. Customer Focus, Passion to Win.

NXP Quality Management Team.

About NXP Semiconductors

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